## 1 Characteristics

Symbol	Parameter	Value	Unit
V <sub>PP</sub>	IEC 61000-4-2 (C = 150 pF, R = 330 Ω) External pins (A2, B2 and C2): level 4 Air discharge Contact discharge Internal pins (A1, B1): level 1 Air discharge Contact discharge	15 8 2 2	kV
Pd	Line resistance power dissipation at 85 °C (top max)	60	mW
Тj	Operating temperature range	- 30 to + 85	°C
T <sub>stg</sub>	Storage temperature range	- 55 to 150	°C

### Table 1. Absolute maximum ratings (T<sub>amb</sub> = 25 °C)

### Figure 3. Electrical characteristics (definitions)

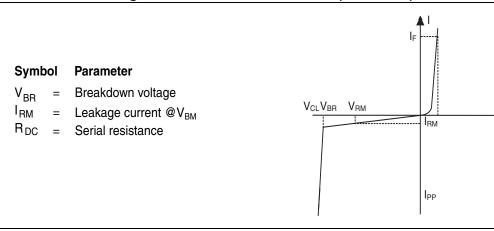


Table 2. Electrical	characteristics	(values,	$T_{amb} = 25 \text{ °C}$
		(141400)	

Symbol	Test conditions		Тур.	Max.	Unit
V <sub>BR</sub>	I <sub>R</sub> = 1 mA	6			V
I <sub>RM</sub>	V <sub>RM</sub> = 3 V per line			100	nA
R <sub>DC</sub>	DC serial resistance		3.4	4.5	Ω



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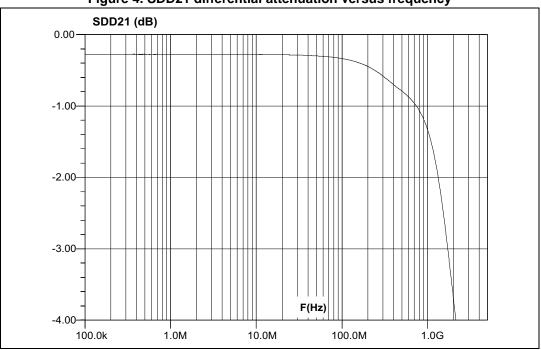
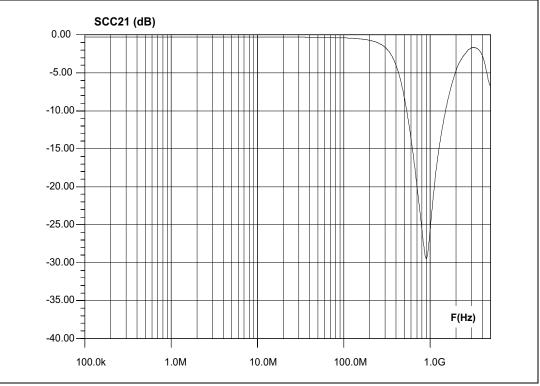


Figure 4. SDD21 differential attenuation versus frequency







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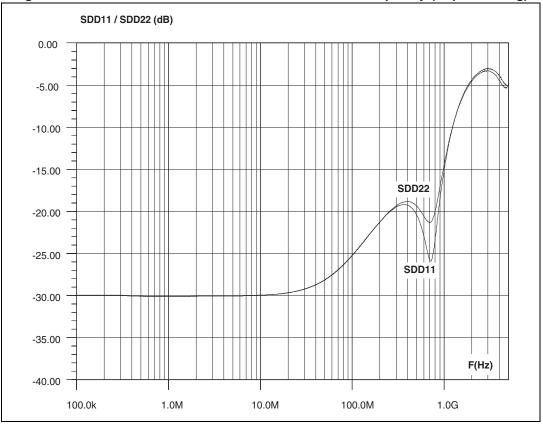


Figure 6. SDD11 / SDD22 differential return loss versus frequency (ID pin floating)

Figure 7. Eye diagram (according to USB 2.0 high speed specification mask1)

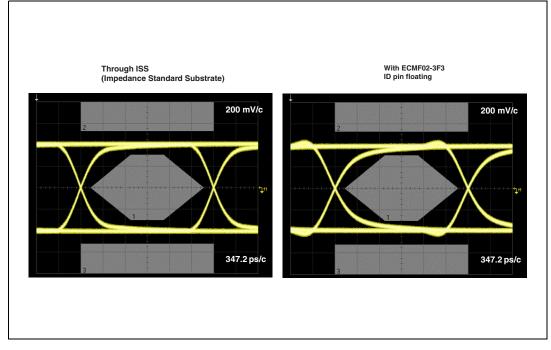
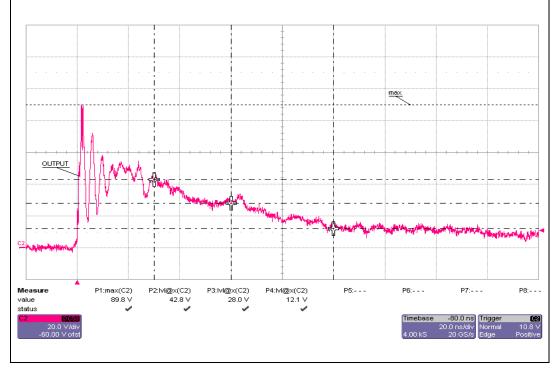






Figure 8. TDR:  $Z_{0 \text{ DIFF}}$  = 100  $\Omega$ ,  $t_{R}$  = 400 ps (10% - 90%),

Figure 9. ESD response to IEC 61000-4-2 (+8 kV contact discharge)





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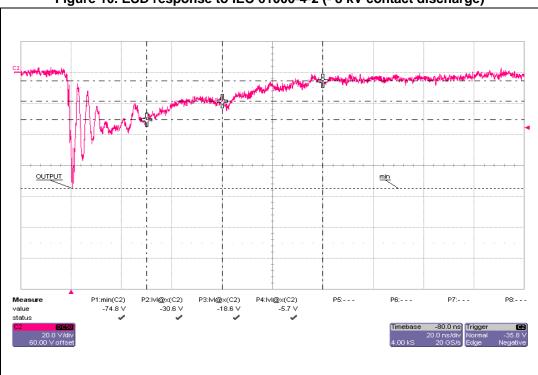


Figure 10. ESD response to IEC 61000-4-2 (- 8 kV contact discharge)



## 2 USB 2.0 application schematic

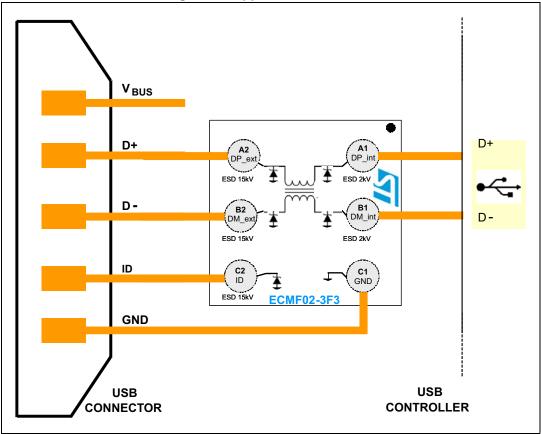


Figure 11. Application schematic



# **3** Ordering information scheme

Figure	12.	Orderina	information	scheme
		• • • • • • • • • • • • • • • • • • •		

	ECMF	02 	-	3	F3
Function ESD common mode filter					
Number of lines 02 = 2 lines					
Number of ESD protected lines 3 = 3 ESD protected lines					
Package F3 = Flip Chip, 0.4 mm pitch					



## 4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: *www.st.com.* ECOPACK<sup>®</sup> is an ST trademark.

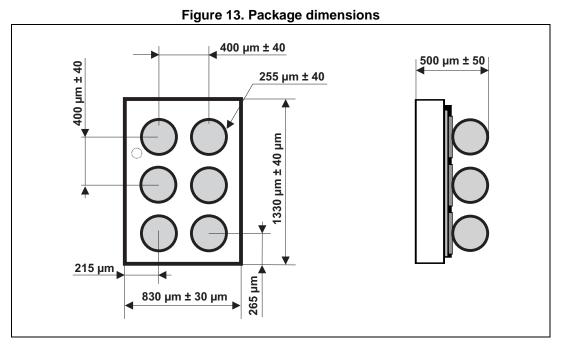
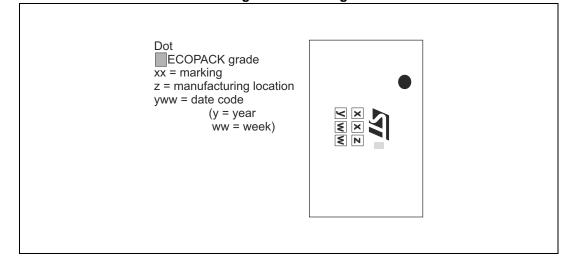
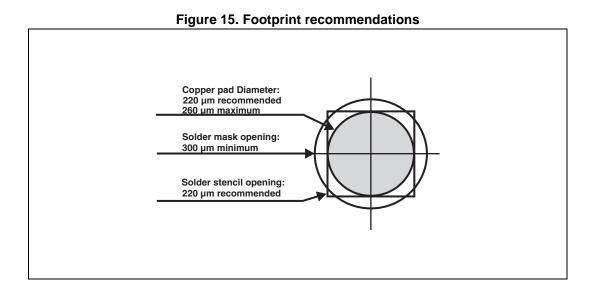
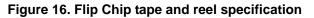


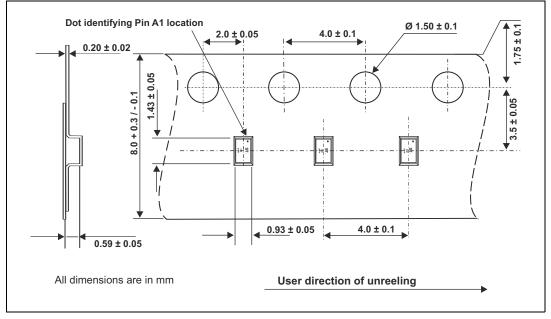
Figure 14. Marking











Note:

More information is available in the application notes: AN2348, "IPAD<sup>™</sup> 400 µm Flip Chip: package description and recommendations for use" AN1751, "EMI filters: recommendations and measurements"



## 5 Ordering information

_						
	Order code	Marking	Package	Weight	Base qty	Delivery mode
	ECMF02-3F3	KH	Flip Chip	1.2 mg	5000	Tape and reel 7"

Table 3. Ordering information

## 6 Revision history

### Table 4. Document revision history

Date	Revision	Changes
19-Nov-2012	1	Initial release.
22-May-2013	2	Moved dot position in <i>Figure 13</i> . Moved arrow in <i>Figure 16</i> to point to pin A1 location.
19-Dec-2013	3	Corrected typographical error in <i>Figure 13</i> .



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